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(12) **United States Design Patent**
Onda et al.

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- (54) **HEAT SINK**
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- (73) Assignee: **ABL IP Holding LLC**, Atlanta, GA (US)

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- (**) Term: **15 Years**
- (21) Appl. No.: **29/575,857**
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- (51) **LOC (11) Cl.** **13-03**
- (52) **U.S. Cl.**
USPC **D13/179**
- (58) **Field of Classification Search**
USPC D13/179, 145, 184; D23/318, 322; D4/127, 128; D28/18, 19
CPC B60H 1/2206; B60H 1/00264; B60H 1/00357; F24H 1/009; F24H 1/06; H05K 7/20172; F28F 2215/00; F28F 2215/02; F28F 2250/00; F28F 3/022; F28F 2215/04; G06F 1/20; F21V 29/80; F21V 29/81; H01L 23/3677; F28D 2021/0029
See application file for complete search history.

(57) **CLAIM**

The ornamental design for a heat sink, as shown and described.

DESCRIPTION

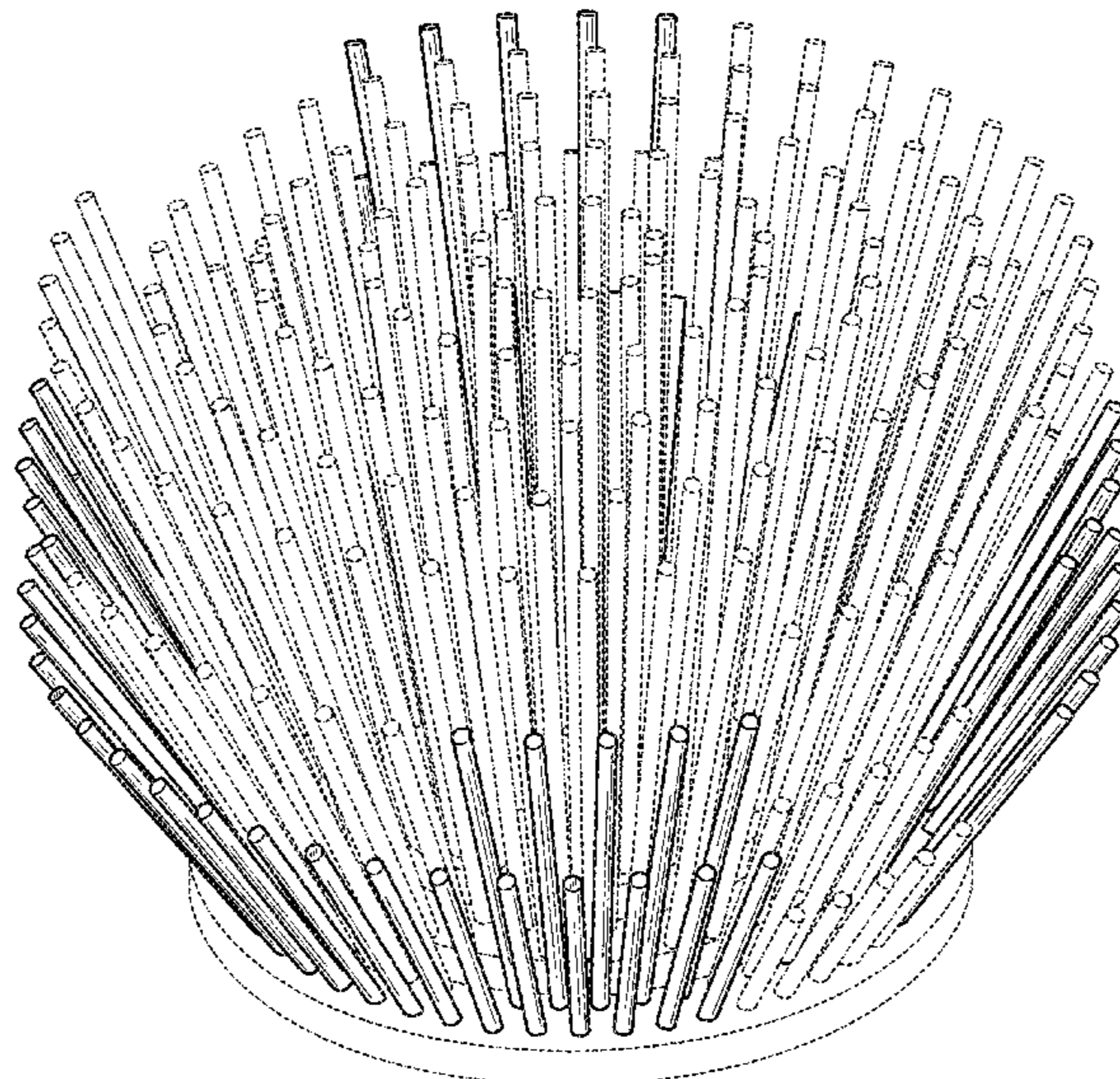
FIG. 1 is a top perspective view of the heat sink.
 FIG. 2 is a left side elevation view of the heat sink of FIG. 1.
 FIG. 3 is a right side elevation view of the heat sink of FIG. 1.
 FIG. 4 is a front elevation view of the heat sink of FIG. 1.
 FIG. 5 is a rear elevation view of the heat sink of FIG. 1.
 FIG. 6 is a top plan view of the heat sink of FIG. 1; and,
 FIG. 7 is a bottom plan view of the heat sink of FIG. 1.
 The evenly dotted broken lines in the drawings illustrate portions of the heat sink and form no part of the claimed design.

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1 Claim, 7 Drawing Sheets



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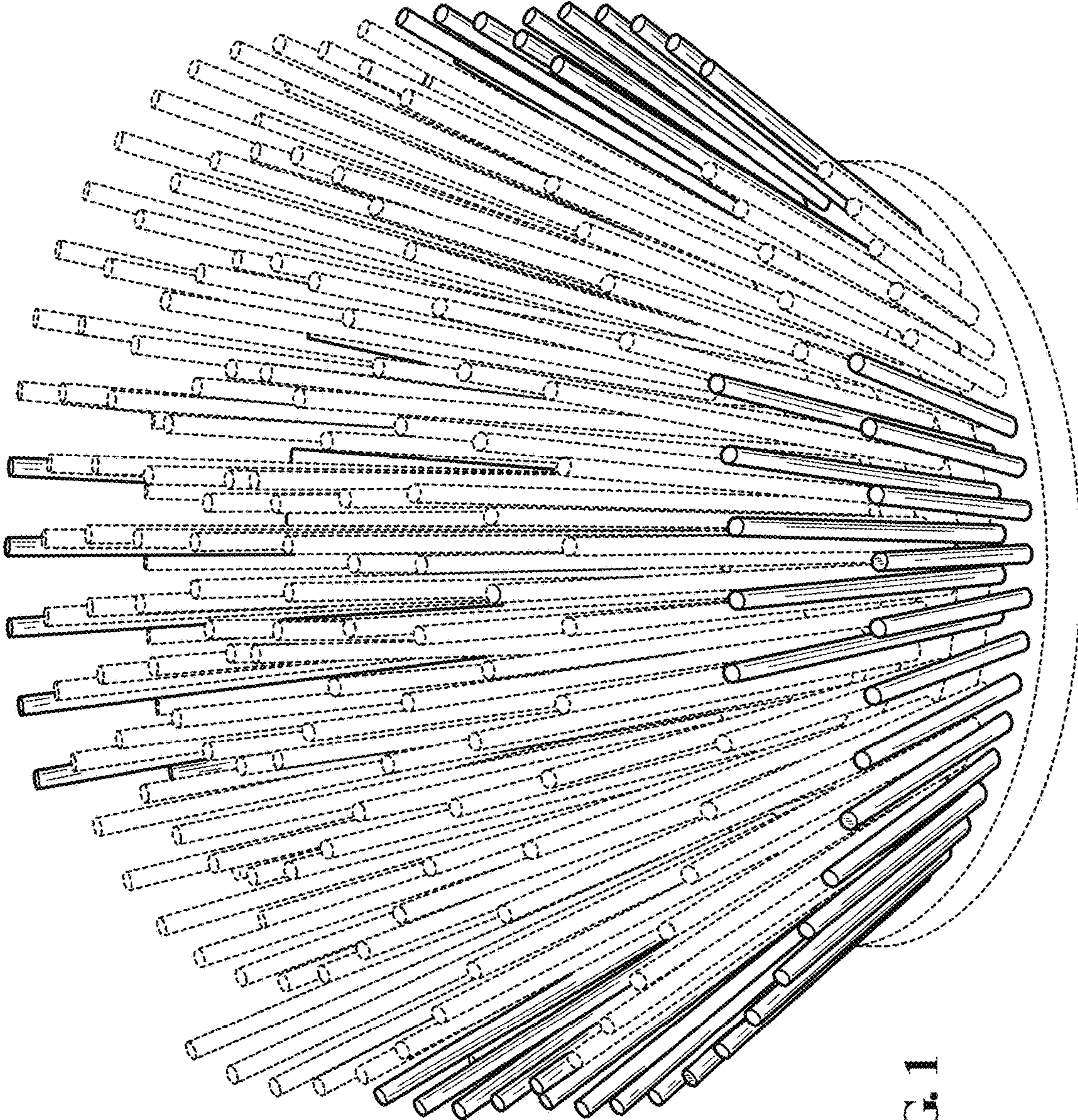


FIG. 1

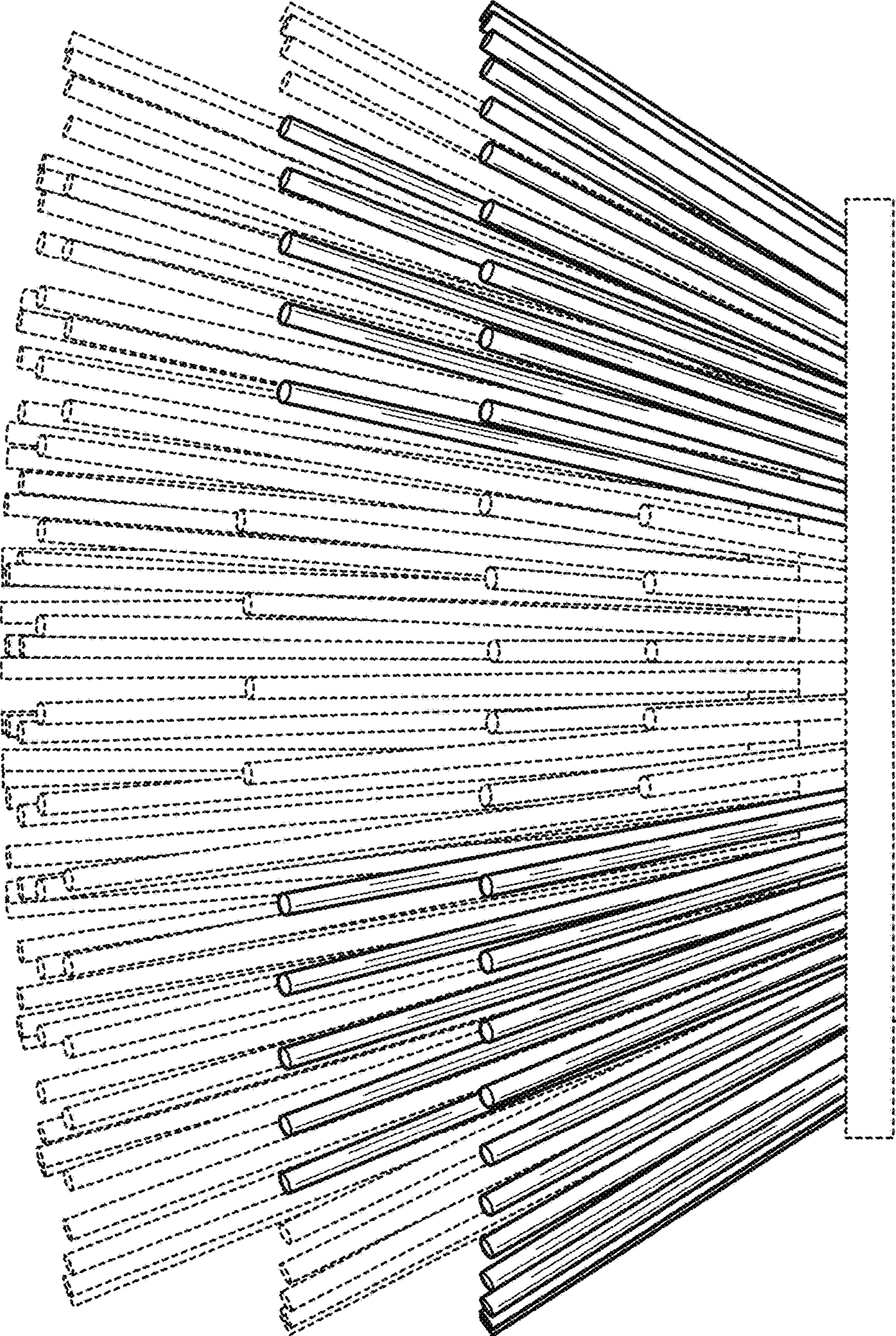


FIG. 2

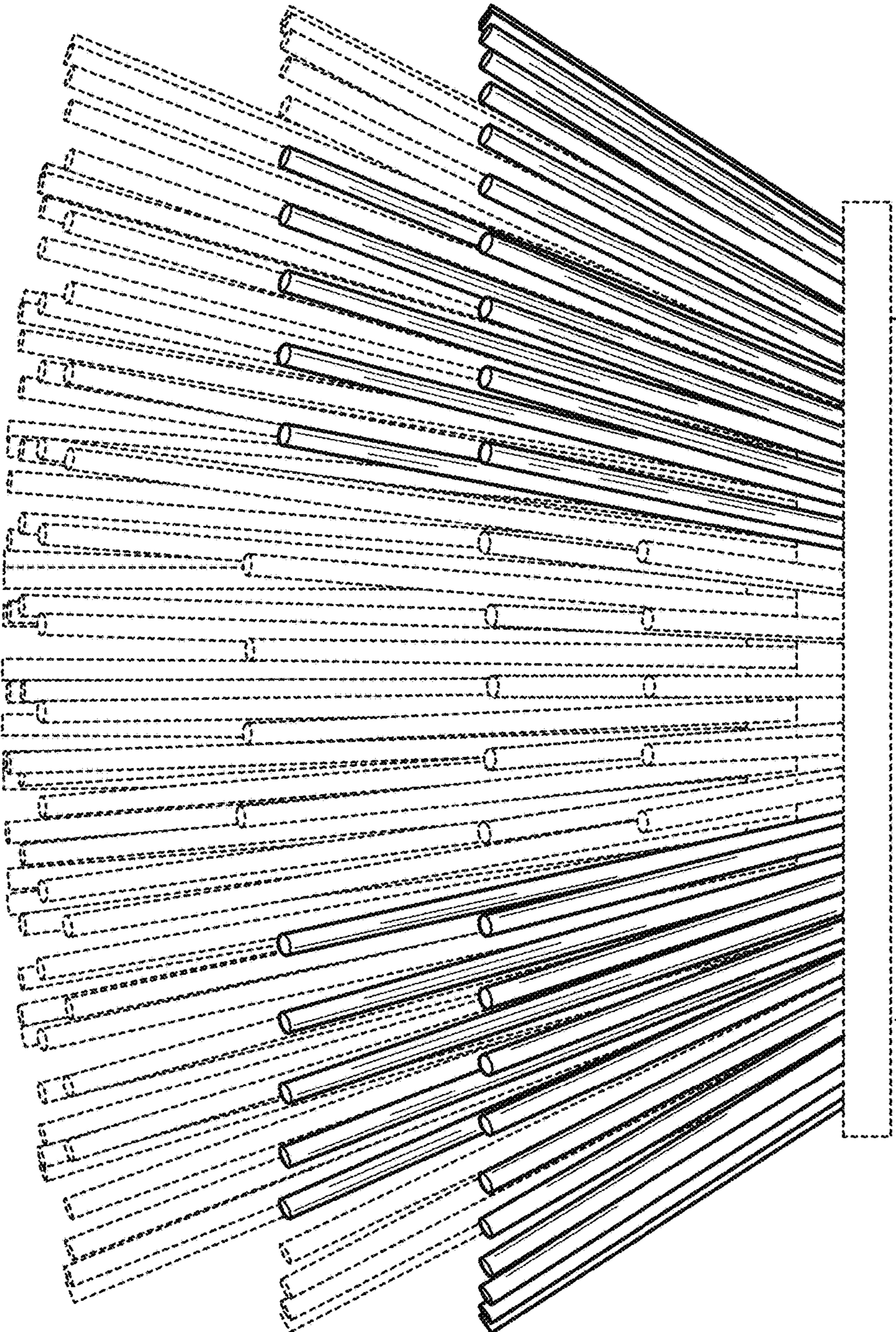


FIG. 3

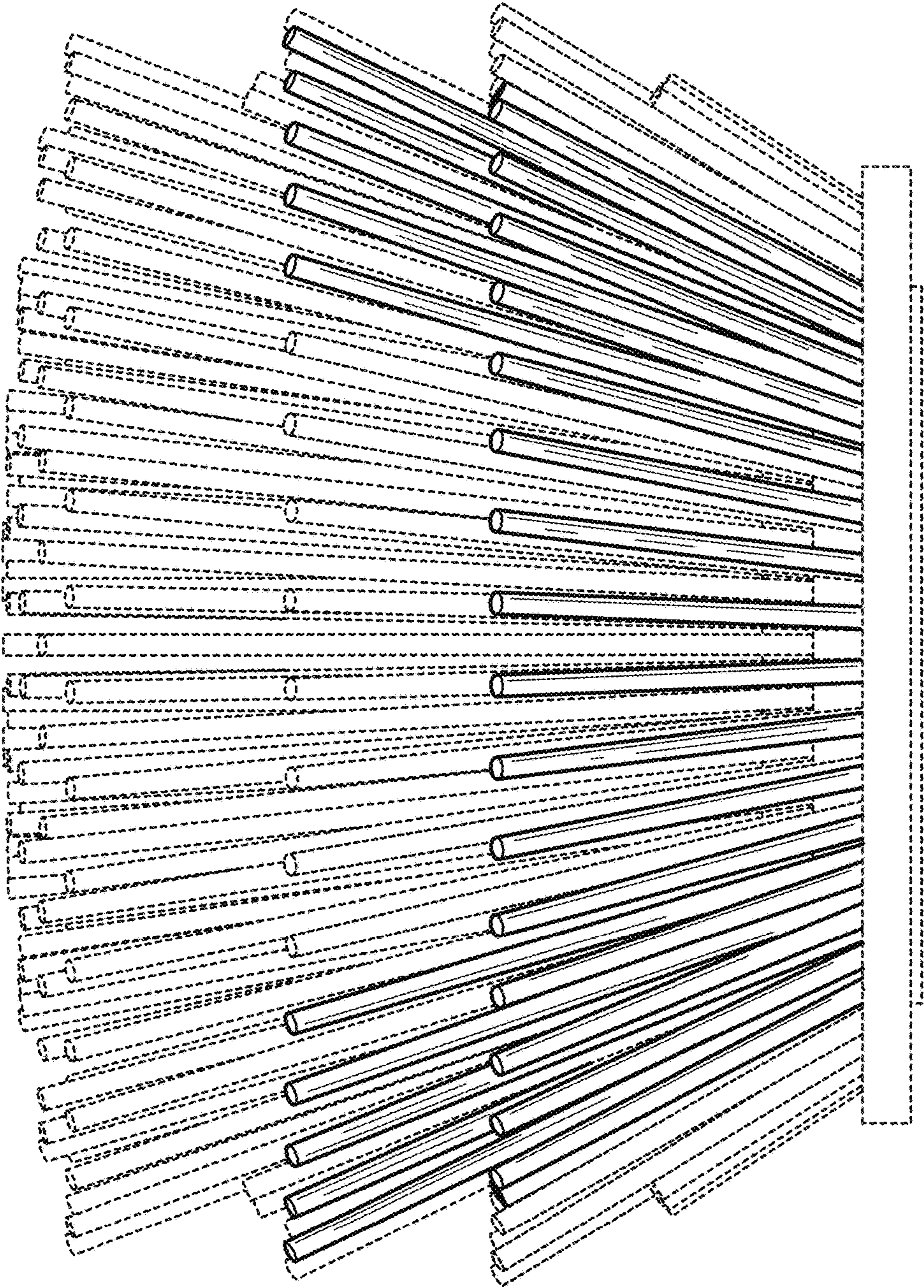


FIG. 4

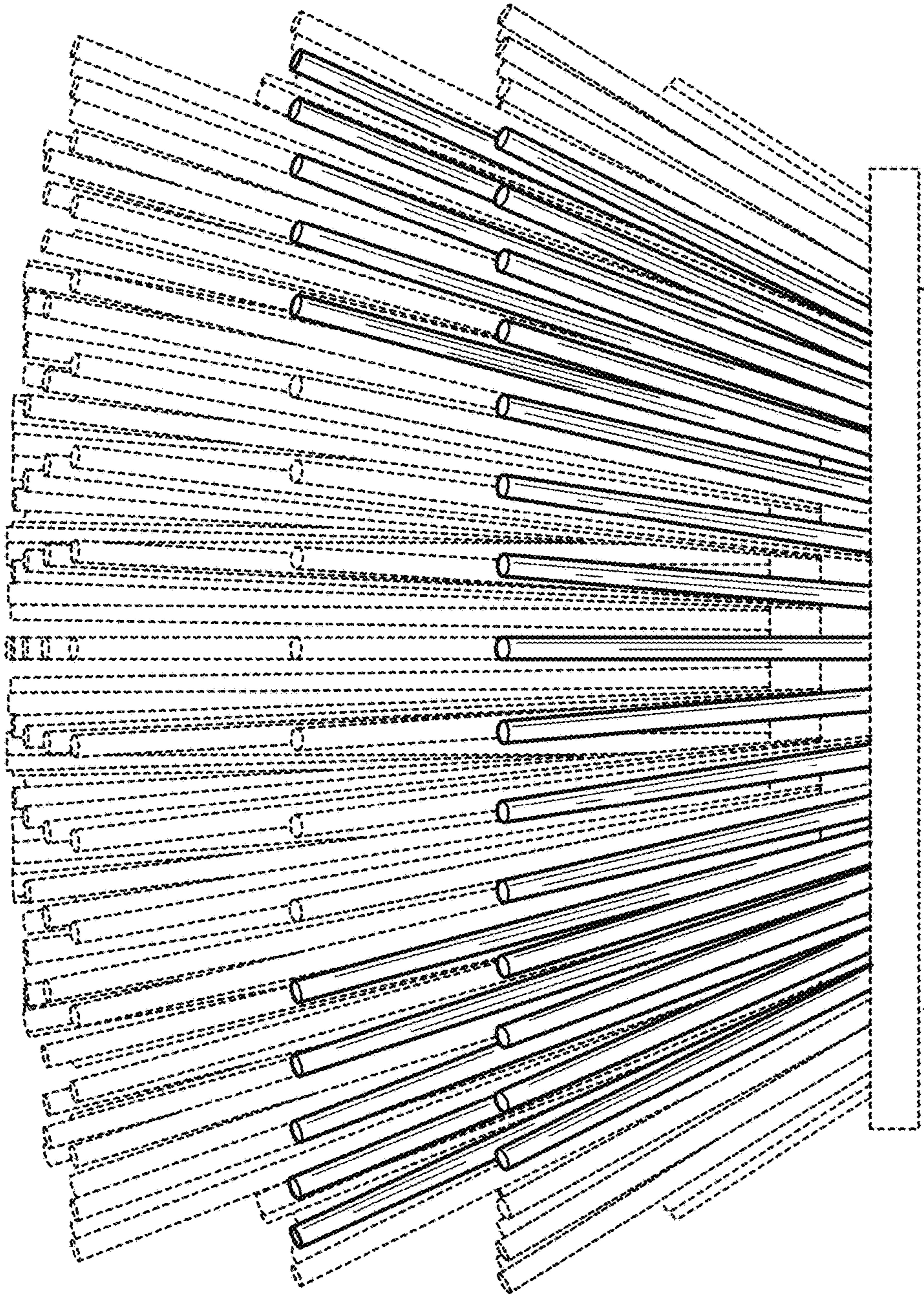


FIG. 5

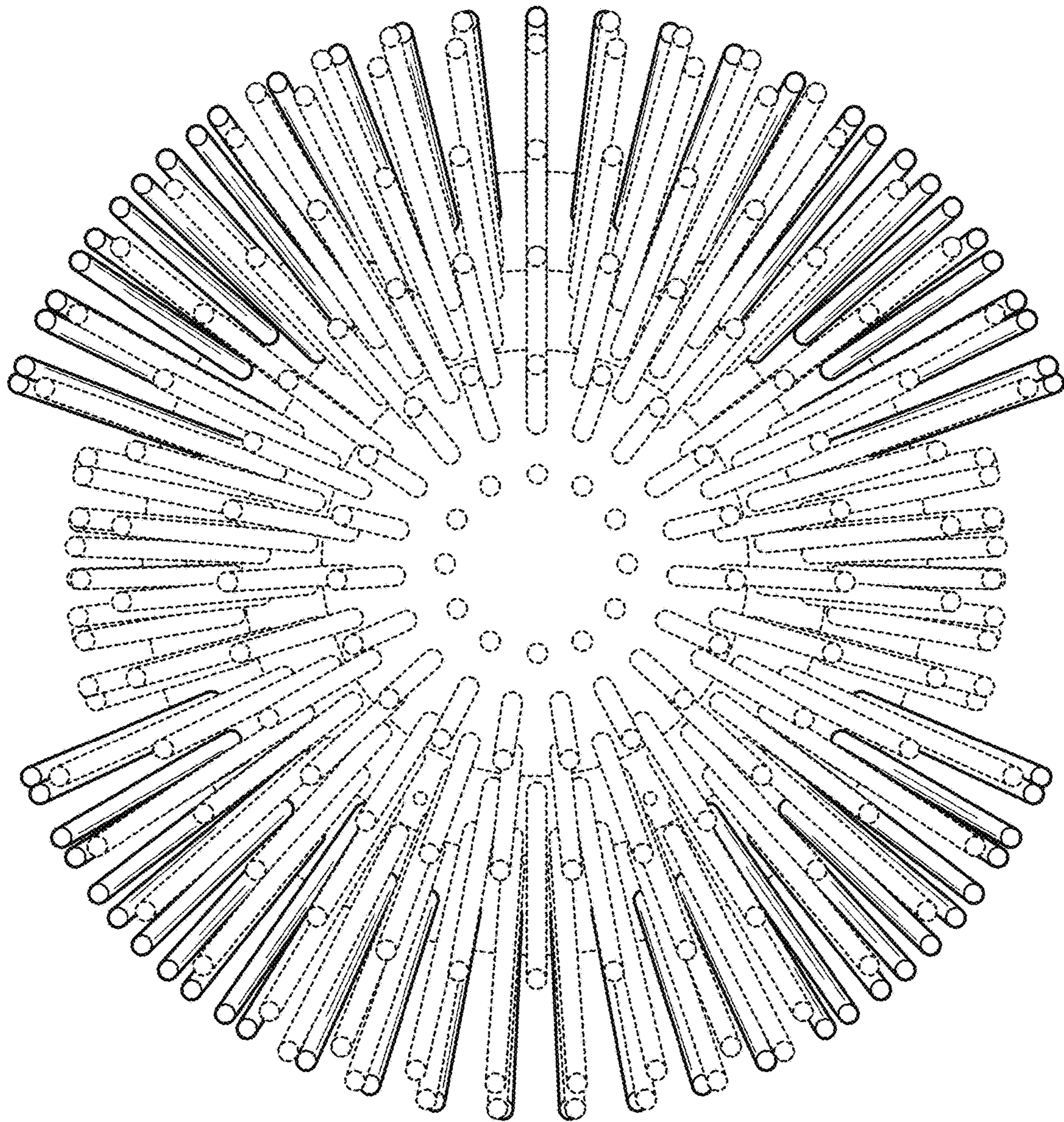


FIG. 6

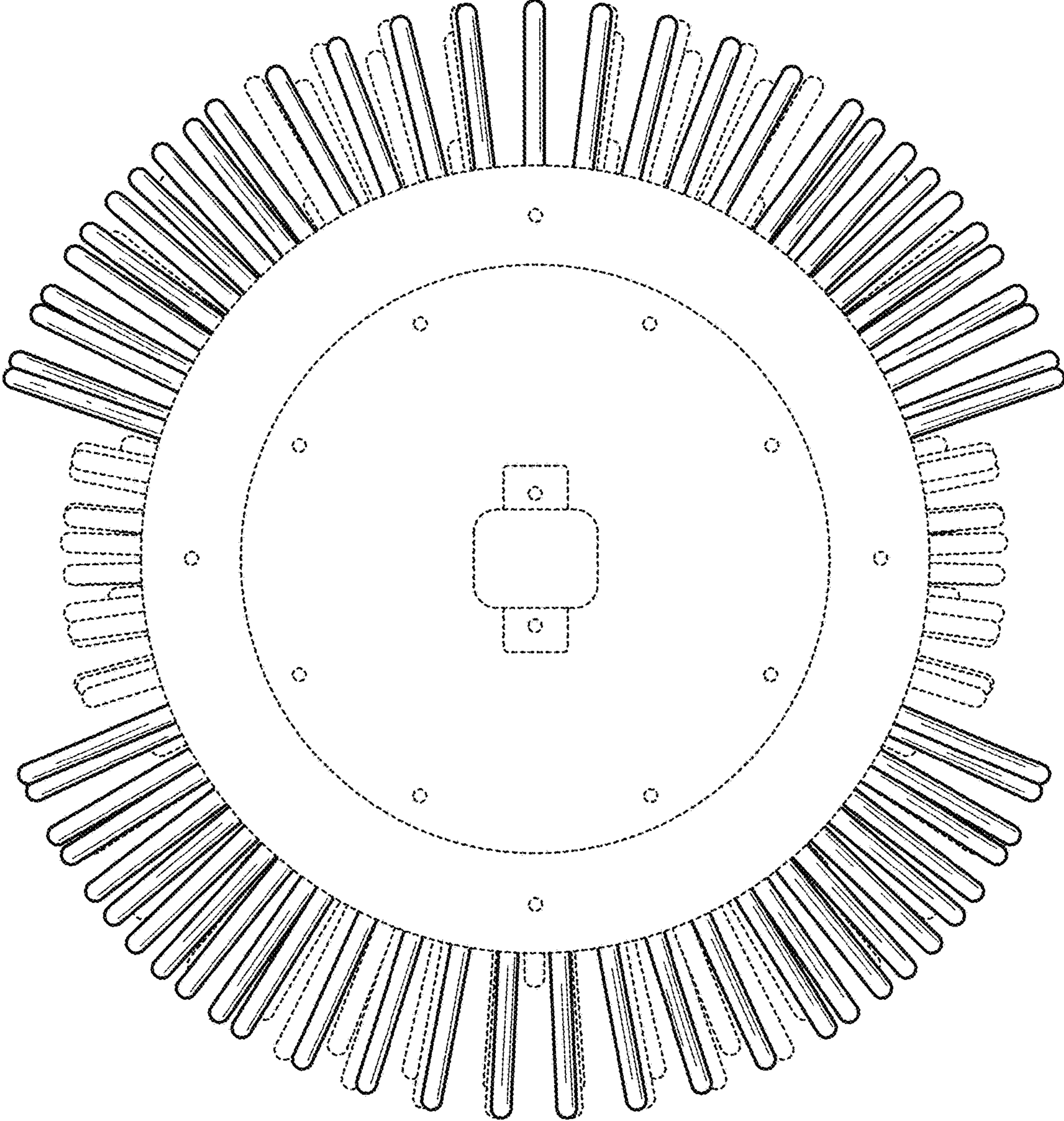


FIG. 7